



Design and Simulation of Electrostatic Protection Device on Semiconductors

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Message from the Guest Editors

Dear Colleagues,

Electrostatic discharge (ESD) is one of the most prevalent threats to the reliability of electronic components. ESD involves the transfer of a finite amount of charge from one object to another, and accounts for more than 35% of all catastrophic chip damage due to single events, as it can result in a very high current passing through the microchip in a very short period of time. However, it is becoming increasingly difficult to meet the progressively more stringent ESD protection requirements for various electronic applications. Latchup also poses a reliability threat, as it may occur during normal chip operation and lead to a runaway event that causes the chip to be destroyed. Therefore, Latchup mitigation solutions are also urgently needed in the semiconductor industry.

The main objective of this dedicated Special Issue is to engage the global ESD and Latchup community in a serious discussion through scholarly contributions specifically focused on solving major challenges in the board area of ESD and Latchup solutions for semiconductor technologies.





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Message from the Editor-in-Chief

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